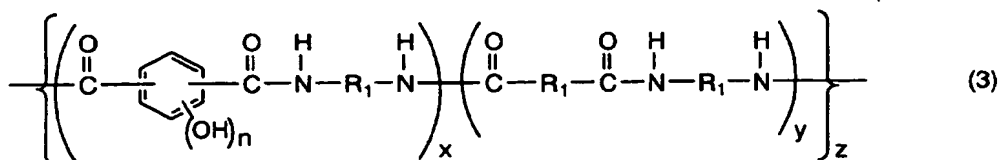


# CLAIMS

1. An adhesive aid composition comprising a phenolic hydroxyl group-containing polyamide and a solvent.

2. The adhesive aid composition according to claim 1, wherein the phenolic hydroxyl group-containing polyamide is a polyamide having a repeat structure represented by formula (3):



(wherein  $\text{R}_1$  represents a divalent aromatic group and  $\text{R}_1$ s in repeat units may be the same or different;  $n$  represents an average number of substituents and is a positive number of 1 to 4; and  $x$ ,  $y$ , and  $z$  represent average degrees of polymerization and are positive numbers of 1 to 10, 0 to 20, and 1 to 50, respectively).

3. The adhesive aid composition according to claim 1 or 2, prepared for a polyimide film.

4. A film prepared by coating a surface of a polyimide precursor with the adhesive aid composition according to claim 1 or 2, and then heating the polyimide precursor.

5. A single-sided copper-clad laminate comprising the film according to claim 4.

6. A double-sided copper-clad laminate comprising the

film according to claim 4.

7. A flexible printed wiring board comprising the film according to claim 4.

8. A multilayer printed wiring board comprising the film according to claim 4.